Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

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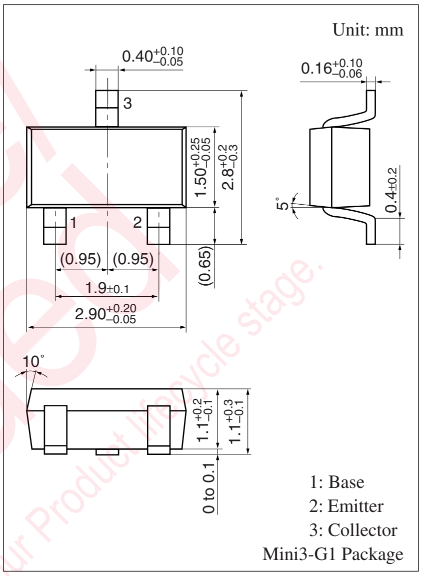
2SD0601A (2SD601A)

Silicon NPN epitaxial planar type

For general amplification
Complementary to 2SB0709A (2SB709A)



Marking Symbol: Z

■ Features

- High foward current transfer ratio h_{FE}
- Low collector to emitter saturation voltage $V_{CE(sat)}$
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	60	V
Collector-emitter voltage (Base open)	V_{CEO}	50	V
Emitter-base voltage (Collector open)	V_{EBO}	7	V
Collector current	I_C	100	mA
Peak collector current	I_{CP}	200	mA
Collector power dissipation	P_C	200	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 10\ \mu A$, $I_E = 0$	60			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 2$ mA, $I_B = 0$	50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10\ \mu A$, $I_C = 0$	7			V
Collector-base cut-off current (Emitter open)	I_{CBO}	$V_{CB} = 20$ V, $I_E = 0$			0.1	µA
	I_{CEO}	$V_{CE} = 10$ V, $I_B = 0$			100	µA
Forward current transfer ratio	h_{FE1} *	$V_{CE} = 10$ V, $I_C = 2$ mA	160		460	—
	h_{FE2}	$V_{CE} = 2$ V, $I_C = 100$ mA	90			
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 100$ mA, $I_B = 10$ mA		0.1	0.3	V
Transition frequency	f_T	$V_{CB} = 10$ V, $I_E = -2$ mA, f = 200 MHz		150		MHz
Noise voltage	NV	$V_{CE} = 10$ V, $I_C = 1$ mA, $G_V = 80$ dB $R_g = 100$ kΩ, Function = FLAT		110		mV
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = 10$ V, $I_E = 0$, f = 1 MHz			3.5	pF

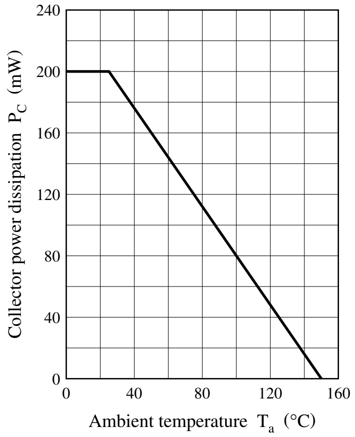
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. *: Rank classification

Rank	Q	R	S	No-rank
h_{FE1}	160 to 260	210 to 340	290 to 460	160 to 460
Marking symbol	ZQ	ZR	ZS	Z

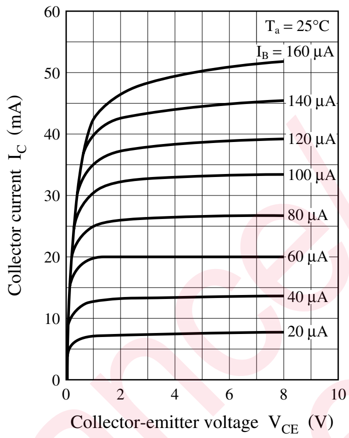
Product of no-rank is not classified and have no marking symbol for rank.

Note) The part number in the parenthesis shows conventional part number.

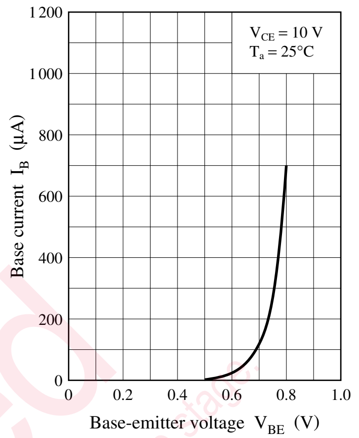
P_C — T_a



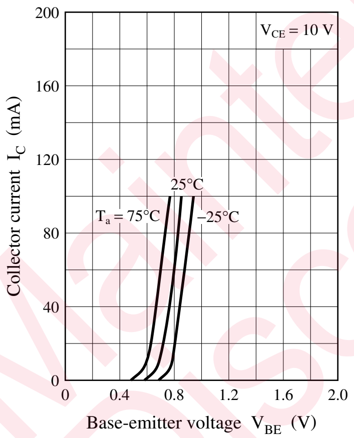
I_C — V_{CE}



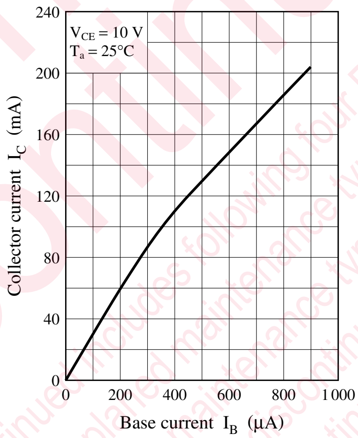
I_B — V_{BE}



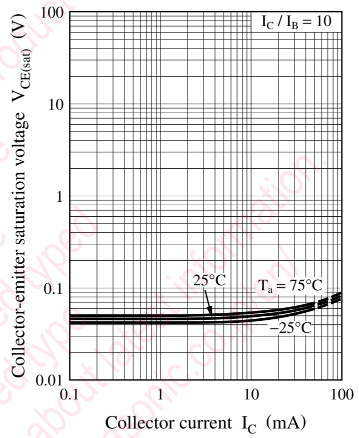
I_C — V_{BE}



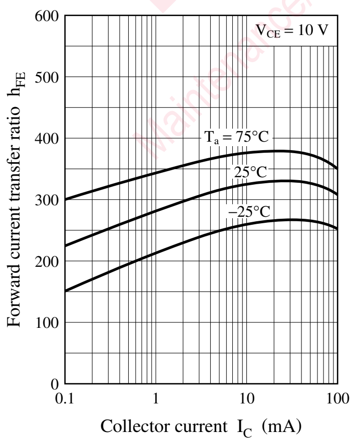
I_C — I_B



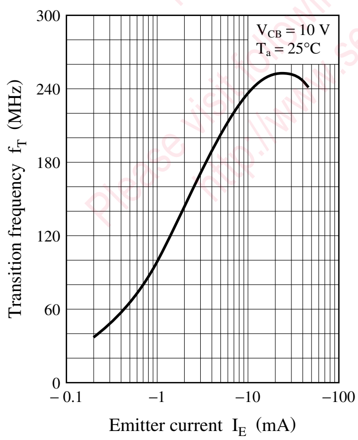
$V_{CE(sat)}$ — I_C



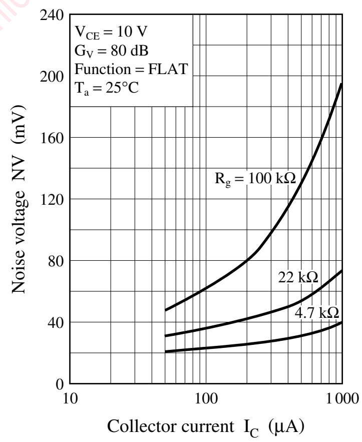
h_{FE} — I_C



f_T — I_E



NV — I_C



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(6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.